



E E ELEKTRONIK HTEEx Series Digital Humidity and Temperature Sensors Instruction Manual

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E E ELEKTRONIK HTEEx Series Digital Humidity and Temperature Sensors



HANDLING INSTRUCTIONS

for the digital humidity and temperature sensors HTE_x

Introduction

This document provides handling instructions for the digital humidity and temperature sensor HTE_x.

Processing Information

Storage Instructions

The digital HTE_x series are highly accurate humidity and temperature sensors. Therefore the storage instructions should be precisely followed. Pursuant to IPC/JEDEC J-STD-020 the Moisture Sensitivity Level (MSL) is 1. At the same time, it is recommended to further process the sensors within 1 year after date of delivery. Please also note that highly concentrated chemical vapors and long exposure times can influence the characteristic of the sensor. It is advisable to keep the sensor package in the original manufacturing packaging. If it is necessary to remove the packaging, ESD trays made from PS (Polystyrol) are recommended, keeping the storage temperature in the range of 0...55 °C. In addition, sealed ESD bags are further recommended.

Soldering Instructions

For mechanical as well as electrical connection the pads have to be soldered to the PCB. The center pad (die pad) may be left floating, anyway it is recommended to connect it to the PCB for accurate measurement results. For the exact dimensions of the land pattern, please see the product datasheet.

For soldering, a standard convection reflow soldering oven may be used (no vapour phase and no wave soldering). For this purpose, a lead-free, air, and nitrogen reflowable no-clean type 3 solder paste, which meets the requirements of the RoHS Directives 2011/65/EU and (EU) 2015/863, as well as the standards by J STD 004 is recommended. Figure 1 below shows a typical soldering profile.

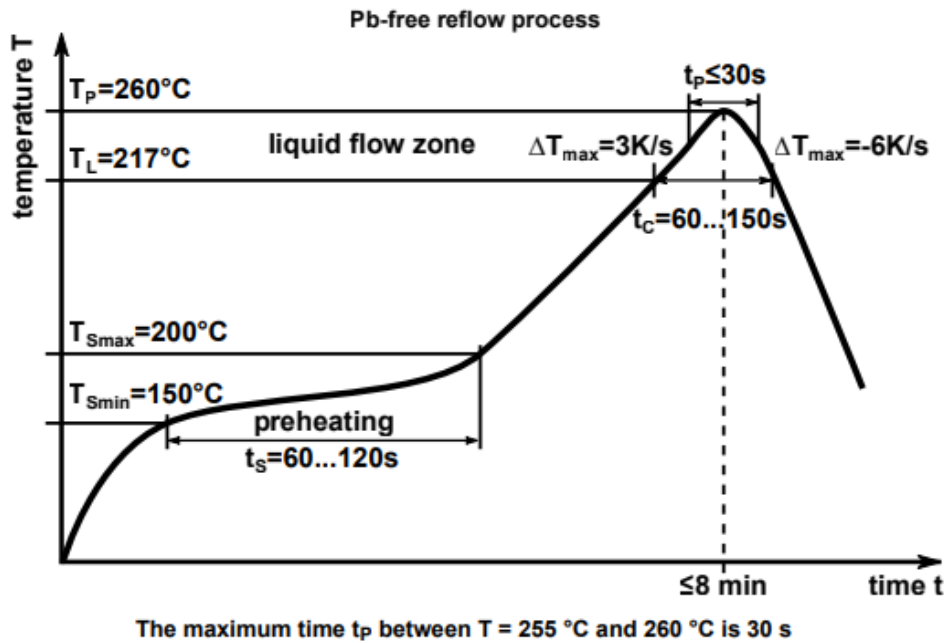


Figure 1: Recommended reflow profile using a standard reflow soldering oven

Please make sure that if there is more than 1 soldering cycle, the sensor is soldered in the last one to avoid contamination of the active surface.

If this is not possible (e.g., selective soldering after the reflow soldering process), the humidity sensor must be covered in such a way that no liquid or gaseous fluxing agents can get onto the humidity sensor.

The sensor is rated MSL 1 according to JEDEC J-STD-020.

Please note that the sensor package itself is qualified to withstand the profile given in JEDEC J STD-020 for lead-free soldering with a peak temperature of 260°C and a time in the critical zone above ($T_{\text{peak}} - 5^\circ\text{C}$) of up to 30 seconds. The packages passed the tests according to: J-STD-0021), AEC Q100, method AEC- Q0052), IEC 60068-2-583), MIL-202 M2104) and IEC 60068-2-215), respectively.

The sensor is assigned a process sensitivity level (PSL) according to EIA/IPC/JEDEC J-STD-075. The PSL is R4Y: The E+E proprietary coating in the sensor opening must not be exposed to flux. The sensors must not be submerged in a cleaning solution.

Post Reflow Treatment

We strongly recommend high humidity storage of the boards including the sensor packages after reflow soldering. 4 – 6 hours at 90 %RH (room temperature) is advisable (see also “moistening” in chapter 2.4.4). Measurement should be done after a short further rest (>1 hour) at room conditions.

General Information

During the whole transportation and manufacturing process it should be avoided to expose the sensor to high concentrations of chemical solvents for extended periods of time. Otherwise, the reconditioning procedure (see chapter 2.4.3) must be followed.

Furthermore, the instructions given in chapter 2.4.1 and 2.4.2 shall be considered. It must be ensured that the sensor is processed according to state of the art electronic manufacturing services.

Recommended Packaging Materials

The best packaging is the original manufacturer packaging. If the sensor has to be removed from this packaging ESD trays made from PS (Polystyrol) or sealed ESD bags are recommended.

Forbidden Packaging Materials

The use of certain outgassing packaging materials such as foams (e.g.: Type MOS 2200) glues, adhesive tapes

and foils shall be avoided since it may change the sensor characteristics.

Reconditioning Procedure

After exposure to extreme conditions or chemical solvents or storage time of several months, the sensor characteristic curve may offset.

Exposure to higher temperature will reset the offset (e.g. 125 °C, 6 hours). For further instructions, see chapter 2.4.4.

If heating up to 125 °C is not possible, the following is suggested:

Store the sensor at 70±5 °C, 75±5 %RH for min. 8 hours to complete the reconditioning process.

1. Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires: Tests B1 and S1
2. Wearout reliability tests, Table 2: Qualification Test Methods, Test E12: lead- (Pb-) free
3. Environmental testing – Part 2-58: Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD) – Test Td1 (group 3), Td2 (group 3)
4. Resistance to soldering heat –Test conditions B and K
5. Environmental testing – Part 2-21: Tests – test U: Robustness of terminations and integral mounting devices – Tests Ue2 and Ue3

Measurements should be done after a short further rest (>1 hour) at room conditions.

Performance Measurement

In order to obtain precise, repeatable and meaningful measurement results, it is absolutely necessary to subject the test samples to a defined procedure consisting of a defined heating and reconditioning step before a characteristic curve can be measured.

The following procedure must be followed:

1. Heat the sensor from room temperature to 125 °C
2. Store them at 125 °C ±5 °C for at least 6 hours.
3. Allow the sensor to cool down to room conditions
4. Moistening:
 1. Store sensor at 23 °C and 90 %RH between 4 and 6 hours
 2. Take 2 measurements at 23 °C and relative humidity between 15 %RH and 95 %RH
5. Perform your characteristic curve measurement

INFORMATION

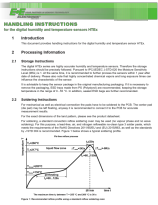
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Documents / Resources



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HTEx Series, Digital Humidity and Temperature Sensors, Humidity and Temperature Sensors, Temperature Sensors, Sensors

References

- [E E Sensor Technology: Humidity, CO2, Flow & Temperature Measurement](#)